

General Description

The series of devices use advanced trench gate super junction technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- Optimized body diode reverse recovery performance
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- LLC Half-bridge



TO-252



Schematic

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS}=0V$)	V_{DS}	900	V
Gate-Source Voltage ($V_{DS}=0V$), AC ($f>1$ Hz)	V_{GS}	± 30	V
Gate-Source Voltage ($V_{DS}=0V$), DC	V_{GS}	± 20	V
Continuous Drain Current at $T_c=25^\circ C$	$I_{D(DC)}$	7	A
Continuous Drain Current at $T_c=100^\circ C$	$I_{D(DC)}$	4.9	A
Pulsed drain current (Note 1)	$I_{DM(pluse)}$	21	A
Maximum Power Dissipation($T_c=25^\circ C$)	P_D	84	W
Derate above $25^\circ C$		0.56	W/ $^\circ C$
Single pulse avalanche current (Note 2)	I_{AS}	1.0	A
Reverse diode dv/dt, $V_{DS} \leq 480V, I_{SD} < I_D$	dv/dt	15	V/ns
Drain Source voltage slope, $V_{DS} \leq 480V$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55...+175	$^\circ C$

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R_{thJC}	1.8	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	R_{thJA}	62	$^{\circ}\text{C}/\text{W}$

Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	900			V
Zero Gate Voltage Drain Current($T_c=25^{\circ}\text{C}$)	I_{DSS}	$V_{DS}=900V, V_{GS}=0V$			1	μA
Zero Gate Voltage Drain Current($T_c=125^{\circ}\text{C}$)	I_{DSS}	$V_{DS}=900V, V_{GS}=0V$			50	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	3		4	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A$		720	800	m Ω
Dynamic Characteristics						
Gate Resistance	R_g	$F=1\text{MHz}, D-S \text{ short}$		28		Ω
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V,$ $F=1\text{MHz}$		595		pF
Output Capacitance	C_{oss}			30		pF
Reverse Transfer Capacitance	C_{rss}			1.7		pF
Total Gate Charge	Q_g	$V_{DS}=660V, I_D=3.5A,$ $V_{GS}=10V$		14.6		nC
Gate-Source Charge	Q_{gs}			3.1		nC
Gate-Drain Charge	Q_{gd}			7.1		nC
Gate plateau voltage	V_{gp}			5.6		V
Switching times						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=660V, I_D=3.5A,$ $R_G=4\Omega, V_{GS}=10V$		32		nS
Turn-on Rise Time	t_r			19		nS
Turn-Off Delay Time	$t_{d(off)}$			51		nS
Turn-Off Fall Time	t_f			14		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I_{SD}	$T_c=25^{\circ}\text{C}$			7	A
Pulsed-Source-drain current(Body Diode)	I_{SDM}				21	A
Forward on voltage	V_{SD}	$T_J=25^{\circ}\text{C}, I_{SD}=7A, V_{GS}=0V$		0.9	1.1	V
Reverse Recovery Time	t_{rr}	$T_J=25^{\circ}\text{C}, I_F=3.5A,$ $di/dt=100A/\mu s$		200		nS
Reverse Recovery Charge	Q_{rr}			1.45		μC
Peak reverse recovery current	I_{rm}			14.5		A

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega, L=10\text{mH}$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

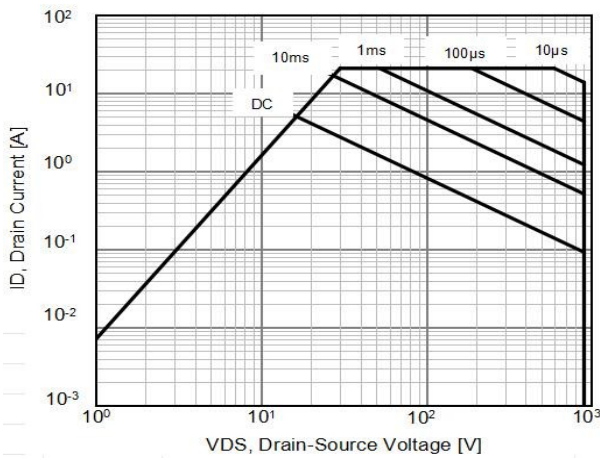
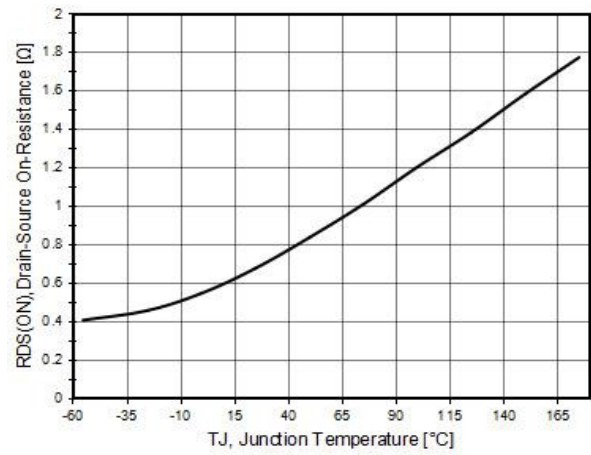
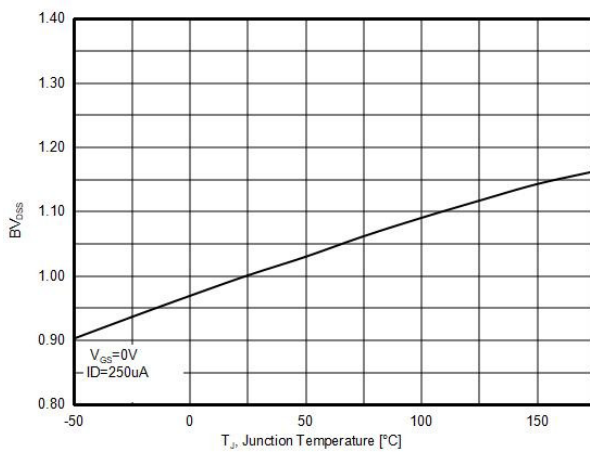
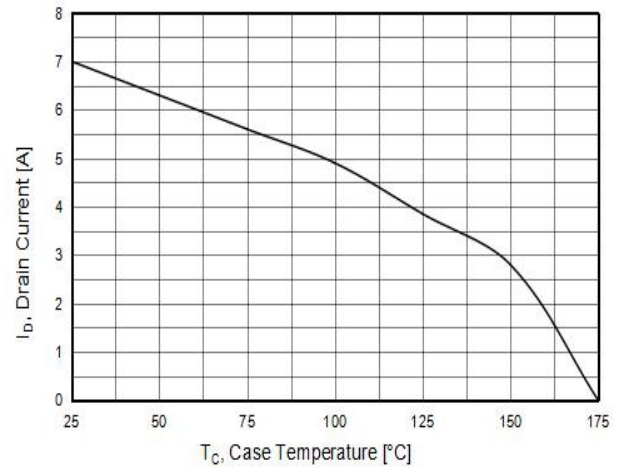
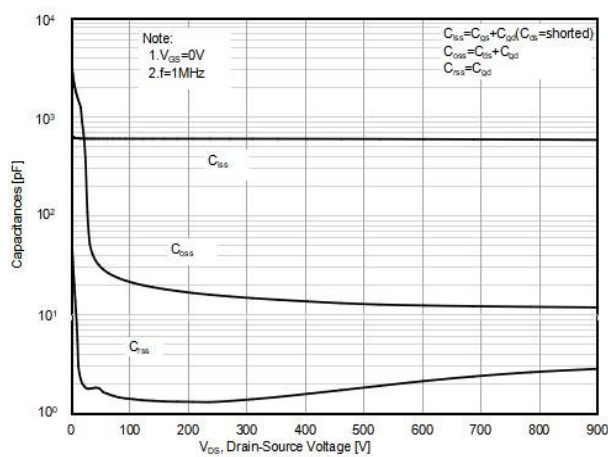
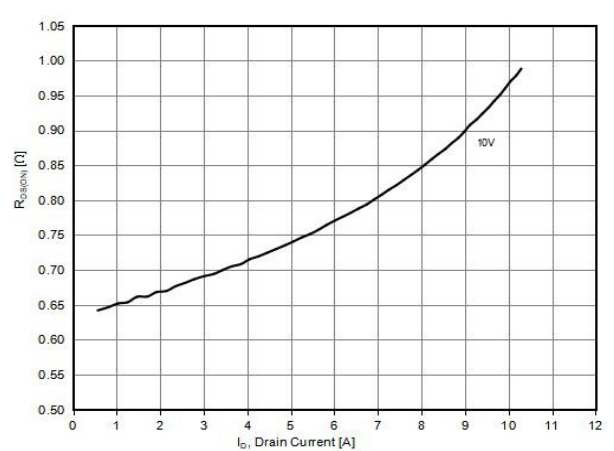
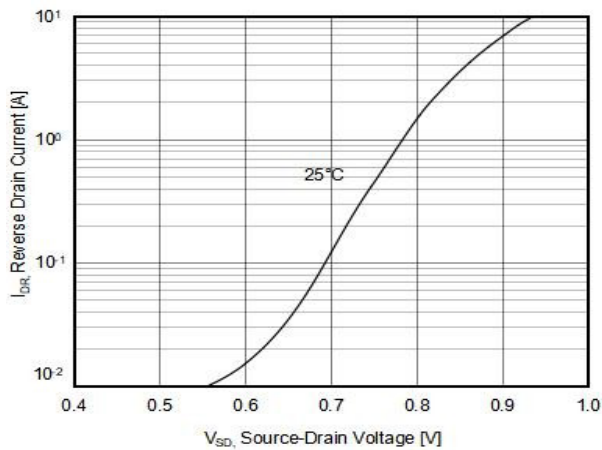
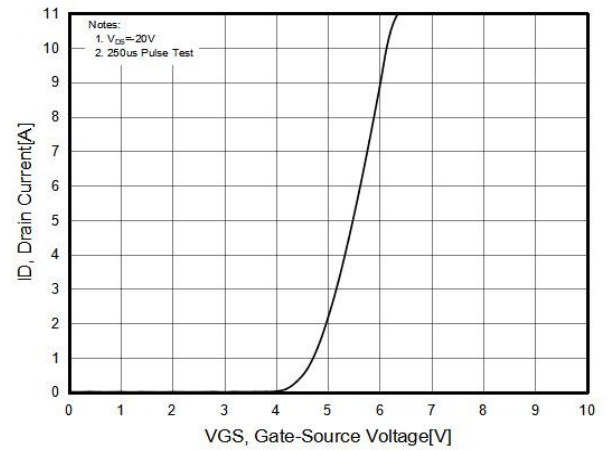
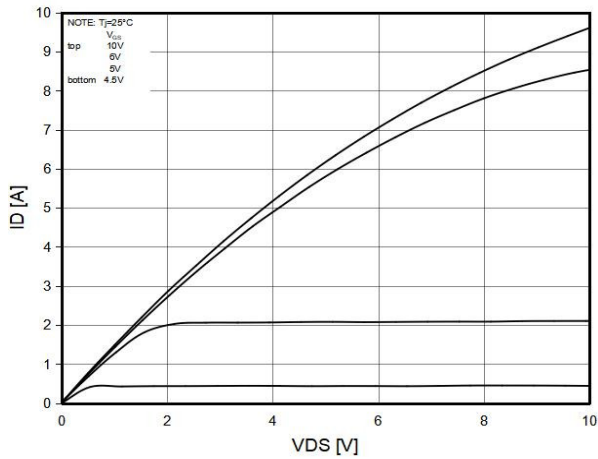
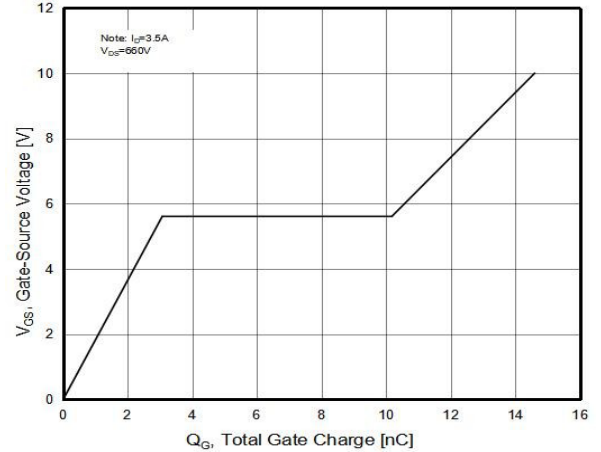
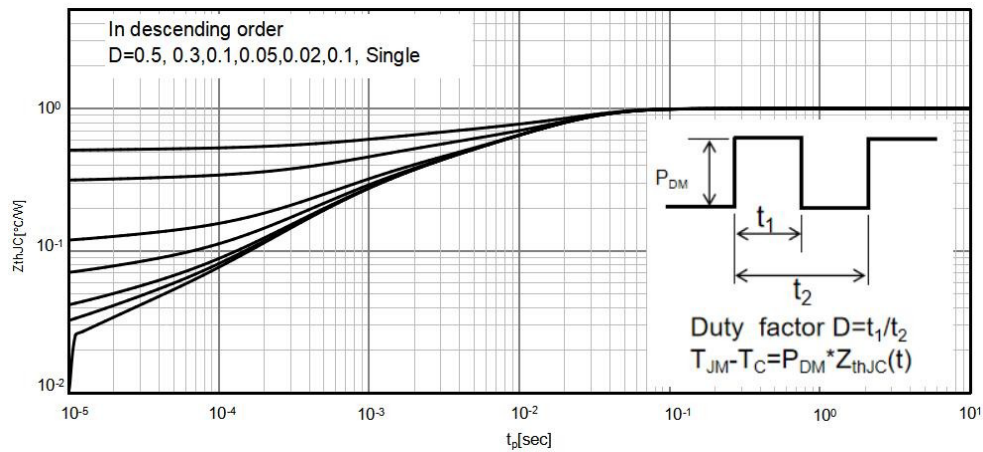
Figure1. Safe operating area

Figure2. $R_{DS(ON)}$ vs Junction Temperature

Figure3. BV_{DSS} vs Junction Temperature

Figure4. Maximum I_D vs Junction Temperature

Figure5. Capacitance

Figure6. Static drain-source on resistance


Figure7. Source-Drain Diode Forward Voltage

Figure8. Transfer characteristics

Figure9. Output characteristics

Figure10. Gate charge waveforms

Figure11. Transient Thermal Impedance


Test circuit

1) Gate charge test circuit & Waveform



2) Switch Time Test Circuit:



3) Unclamped Inductive Switching Test Circuit & Waveforms

